

**Final Product Change Notification**

201912002F01

**Issue Date:** 31-Dec-2019  
**Effective Date:** 30-Mar-2020

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**Management Summary**

Improved BOM of leadless 5/6 pad packages, including die optimization to achieve zero delamination in ATSN (Nexperia Assembly & Test Plant Seremban Malaysia)

**Change Category**

- |  |  |  |   |   |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process   | <input type="checkbox"/> Assembly Process              | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Location  | <input checked="" type="checkbox"/> Design              |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location  | <input type="checkbox"/> Assembly Location             | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |

Improved leadless 5/6 pad packages incl die optimization to achieve zero delamination

**Details of this Change**

Improved BOM of leadless 5/6 pad packages, including die optimization to achieve zero delamination in ATSN (Nexperia Assembly & Test Plant Seremban Malaysia)

- Where necessary optimized die for legacy leadless packages
- Improved die aspect ratio and bond-pad relocation to improve intrinsic quality for wire-bond process and support zero delamination
- Identical IP used resulting in same performance as existing die
- BOM change for zero delamination performance
- Enhanced mould compound
- Introduced rough PPF inner leadframe
- Changed lead finish from Sn to enhanced NiPdAu (alignment with packages which were released since 2015)
- No change in diffusion fab, assembly location or ordering part number

**Why do we implement this Change**

To improve the intrinsic quality

**Identification of Affected Products**

The changed products can be identified by backward traceability of the product marking date code as well as on the reel and box labels

**Product Availability**

**Sample Information**

Samples are available upon request

Samples are available upon request from the Logic sample store Nijmegen The Netherlands

### Production

Planned first shipment 30-Mar-2020

#### Impact

SOT886/1202/1115: No change

SOT1226/1255: No change in fit, function, quality or reliability anticipated. Pads have rounded edges to enhance adhesion/locking. No change on recommended solder footprint

#### Disposition of Old Products

Existing inventory will be shipped until depleted

#### Timing and Logistics

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 30-Jan-2020. Lack of acknowledgement of the PCN constitutes acceptance of the change.

#### Remarks

- No change in data sheet electrical specification, test limits and distributions
- No assembly location change
- No fab location change
- Outline drawing products with SOT1226 and SOT1255 will show rounded edges on pads. (A new datasheet will be issued)

#### Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact Nexperia "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support team.

At Nexperia B.V. we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

#### About Nexperia B.V.

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Jonkerbosplein 52 6534 AB Nijmegen, The Netherlands

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**Affected Part Number**

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74AXP1T32GXZ	74AUP1T17GXH	74LVC1T45GS,132	74LVC1G66GN,132
74LVC1G97GXZ	74AUP1T50GXH	74AUP1G19GM,115	74LVC1G14GS,132
74AUP2G14GM,115	74AUP1T14GXH	74AUP2G07GM,115	74LVC1G3157GN,132
74AUP2G06GM,132	74AUP1T04GXH	74AUP2GU04GM,115	74AXP1T34GSH
74AVC1T45GM,115	74AUP1T00GXH	74AUP1G32GM,115	74LVC1T45GM,132
74LVC1G3157GM,115	74AUP1T02GXH	74AUP1G79GM,115	74LVC1G66GM,115
74AXP2G14GSH	74AUP1T08GXH	74AUP1G14GM,115	74AUP1G09GS,132
74LVCH1T45GM,132	74AVCH1T45GM,115	74LVC1T45GM,115	74LVC1G125GXH
74LVC1G126GM,115	74LVC2G34GM,115	74AUP1G09GM,115	74AUP1G11GM,115
74AUP1G157GM,115	74AUP1G00GN,132	74LVC2G17GM,132	74AXP1G125GXH
74LVC1G08GM,115	74AUP1GU04GM,115	74LVC1G17GM,115	74AXP1G00GMH
74AXP1G00GSH	74AXP1T125GSH	74LVC1G34GM,115	74LVC1G07GM,115
74AUP1G97GM,115	74AUP1G332GM,115	74LVC1G02GM,115	74AUP1G08GM,115
74AXP1T125GNH	74LVC2G04GM,115	74LVC1G32GM,115	74AVC1T45GN,132
74AXP1T34GXH	74LVC2GU04GS,132	74LVC1G80GM,115	74AXP1G125GMH
74LVC1G332GM,115	74LVC1G3157GXZ	74LVC1G125GM,115	74AHC1G125GM,132
74LV1T34GXH	74LVC1G332GXZ	74LVC1G57GM,115	74AVC1T45GS,132
74LV1T86GXH	74AUP2G16GMH	74LVC1G58GM,115	74LVC1G04GM,115
74LV1T87GXH	74AUP1G06GS,132	74AUP1G373GM,115	74AUP1G79GM,132
74LV1T126GXH	74AUP1G08GS,132	74LVC1G11GM,115	74AXP1T14GXH
74LV1T08GXH	74LVC1GU04GX,125	74AUP1G57GM,115	74AXP1T34GMH
74LV1T02GXH	74LVC1G27GM,115	74AUP2G17GM,132	74AXP1T34GNH
74LV1T04GXH	74LVC1G97GM,132	74AUP1G04GX,125	74AXP1T125GMH
74LV1T32GXH	74AUP1G86GS,132	74LVC1G17GX,125	74AHCT1G125GM,132
74AUP1T86GXH	74AUP2G34GS,132	74LVC2G14GM,115	74LVC1G86GM,115
74LV1T125GXH	74LVC1G04GS,132	74AUP1G14GX,125	74AUP2G34GM,115
74AUP1T87GXH	74LVC1G125GS,132	74AUP1T34GXH	74LVC2G17GN,132
74LV1T00GXH	74LVC1G3157GS,132	74AUP1T57GM,115	74AUP1T34GM,115
74AUP1T32GXH	74LVC1G34GS,132	74AXP1G08GMH	